

System-Level Exploration for 3D MPSoCs including Optical Networks-on-Chip

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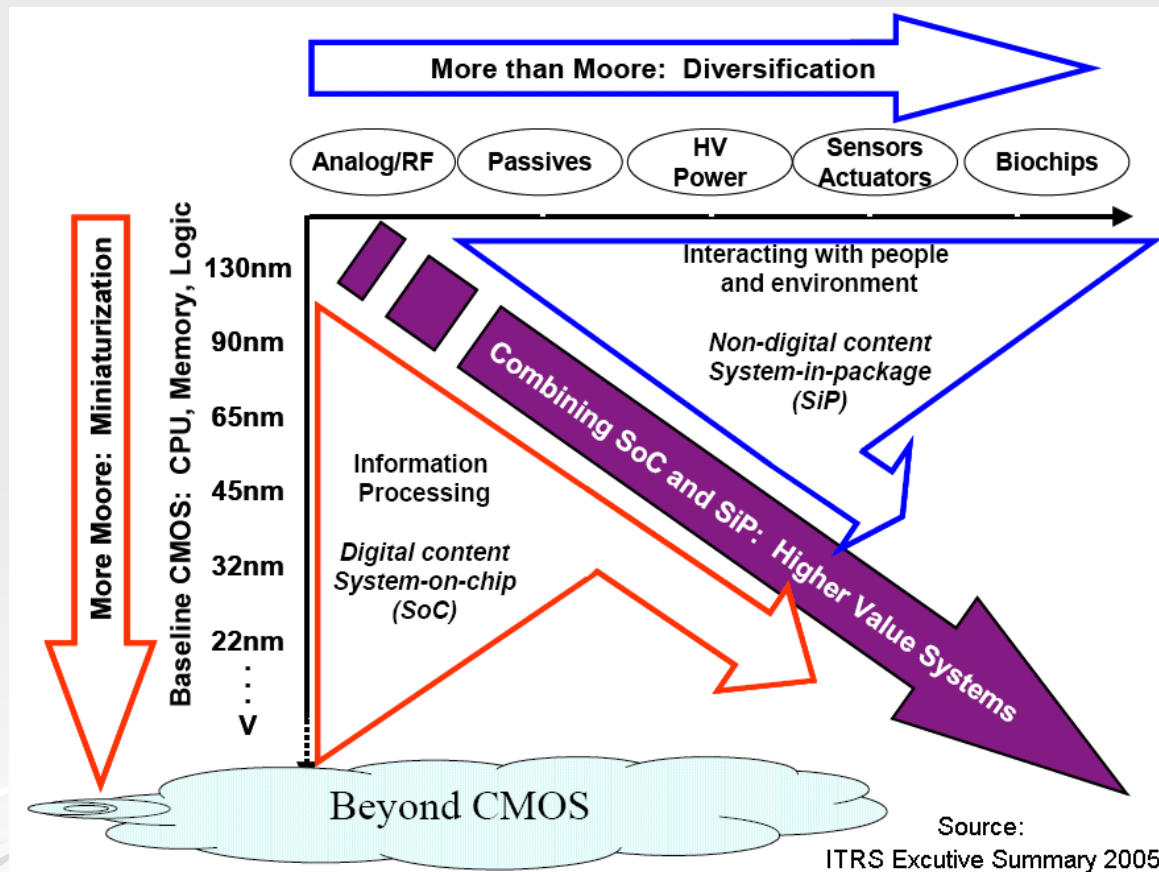
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3D Integration Technology

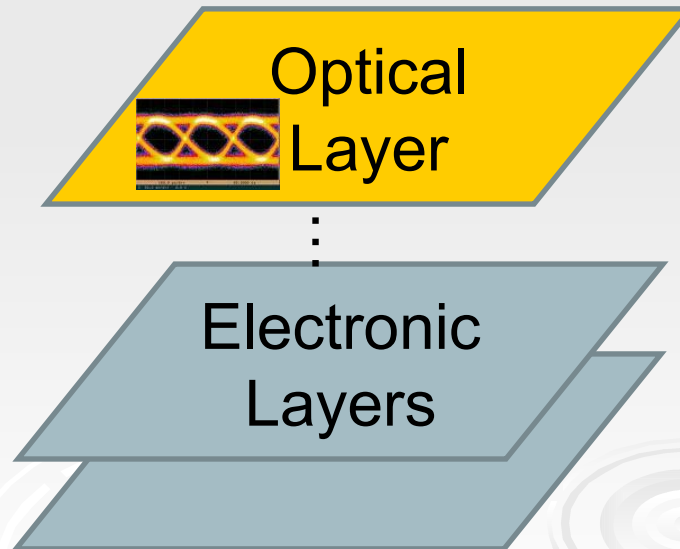
SoC and System-in-Package Convergence

- Higher performance
 - More Moore
- Extended functionalities
 - More Than Moore
 - Equivalent Scaling



3D Integration Technology

- Promising paradigm for Heterogeneous Systems
 - Multiple layers → multiple technologies
 - Functions will use the best technology available
 - Ex. computing → electronics
 - communication → optics



System-Level Exploration for 3D

- Research is technology-dominated
 - Physical level research
 - New devices and architectures are defined
- System-level vision required
 - Cooperation between system-level and physical-level designers

3D MPSoC Including Optical Networks-on-Chip

- Architecture defined by extrapolation of 2 planar approaches :
 1. Optical Network on Chip
 2. Electrical Network on Chip

3D MPSoC Including Optical Networks-on-Chip

➤ Architecture defined by extrapolation of 2 planar approaches :

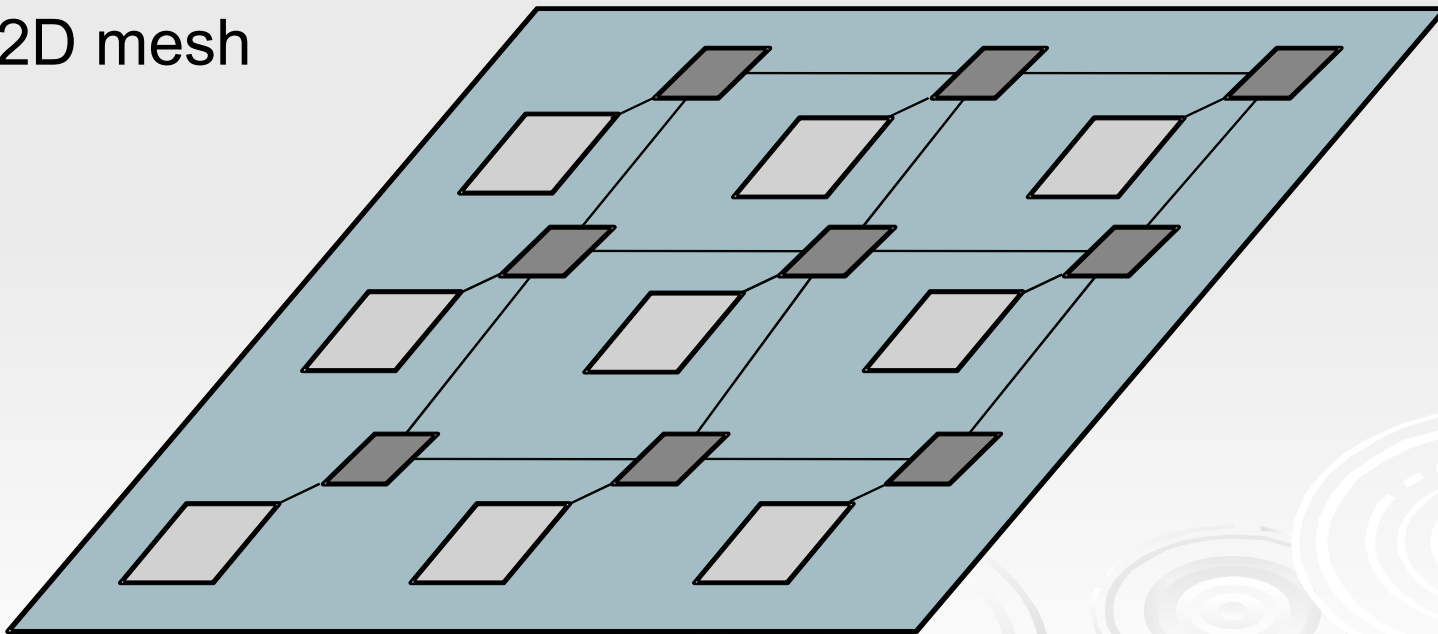
1. Optical Network on Chip

- Multiple signals of different wavelengths in the same waveguide
 - No contention, high bandwidth density → 20 GB/s
 - Simple, scaleable interconnect
- Constant latency (<1 ns), function of:
 - Optical index of transmission medium (Si) → propagation delay
 - Waveguide length
- Frequency limited by optical/electrical interfaces
 - Currently 3.2Gb/s optical (32bits@100MHz electrical)
- Simpler programming models

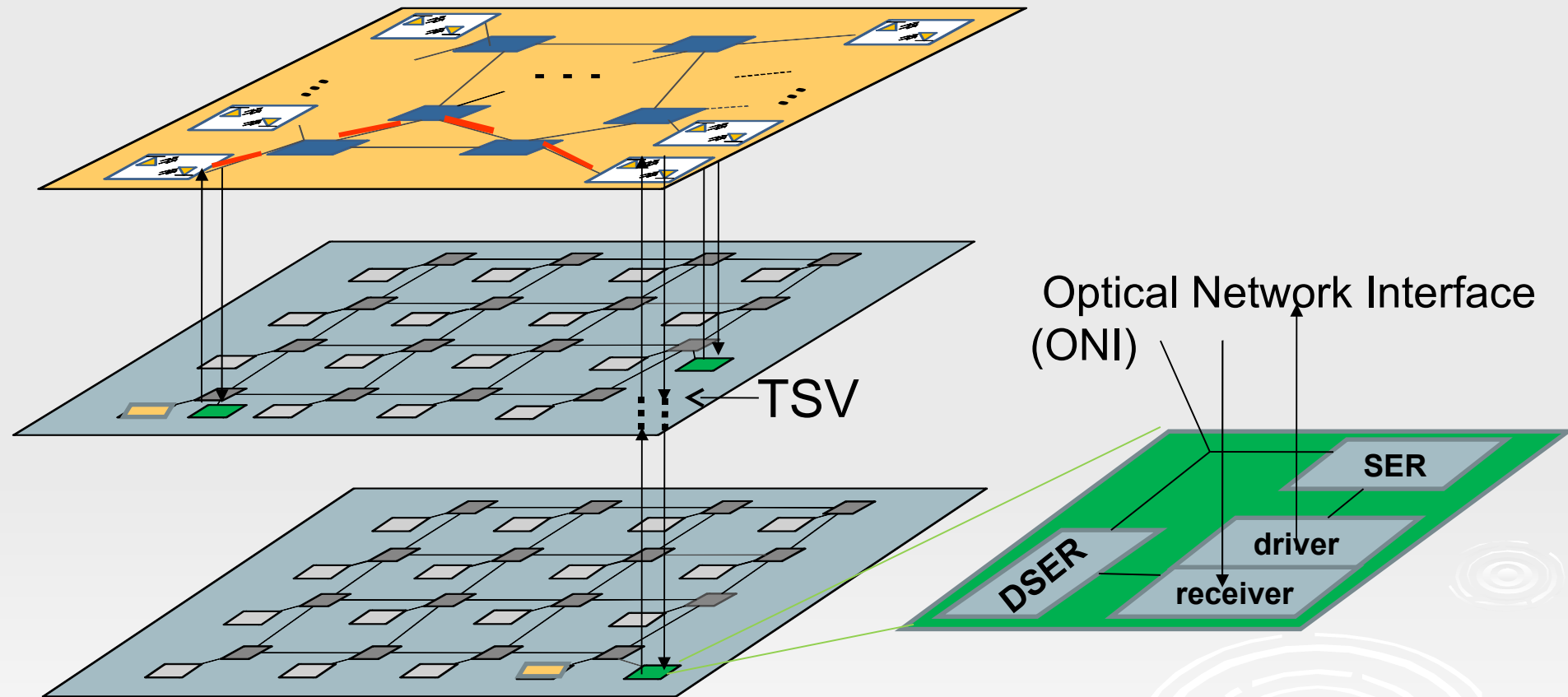
3D MPSoC Including Optical Networks-on-Chip

- Architecture defined by extrapolation of 2 planar approaches :
 1. Optical Network on Chip (ONoC)
 2. Electrical Network on Chip

2D mesh



3D MPSoC Architecture



$$\text{Interconnection Strategy (IS)} = \frac{\text{No of Switches Connected to an ONI}}{\text{Total No. of Switches}}$$

System-Level Exploration for 3D MPSoC Integrating ONoC

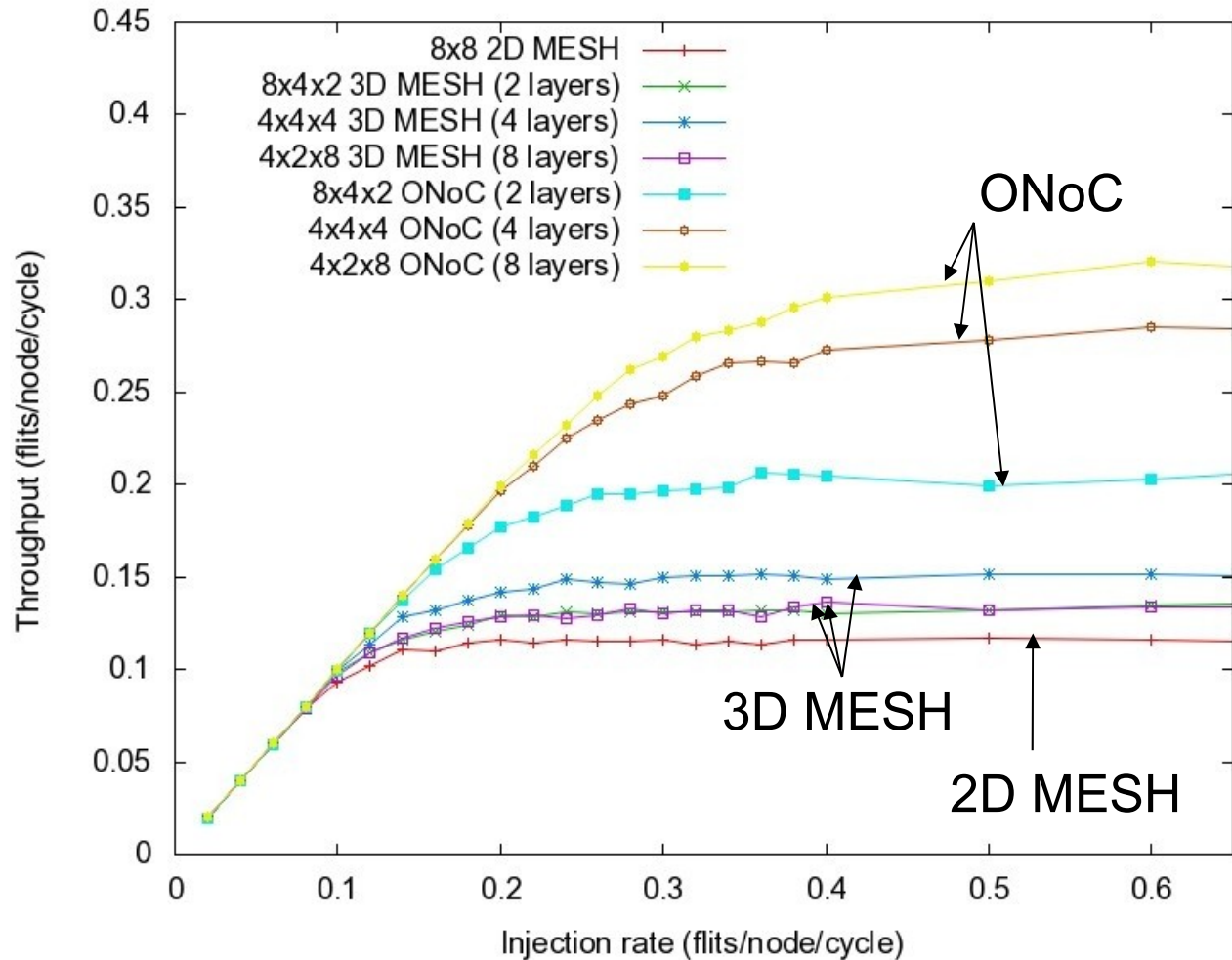
- Internally Developed Event-Based Simulator
 - adapted for 3D MPSoCs
 - Integrating ONoC models
- Electrical routing resources are characterized by bandwidth capability and latency
- Optical Network Interfaces are modeled at transmitter and receiver level and their latency and bandwidth are considered
- Waveguides and optical switches are considered latency free
- Optical switches are characterized by their resonant wavelenath

System-Level Exploration for 3D MPSoC Integrating ONoC

- Configuration parameters
 - The number of electrical layers
 - The number of nodes per layer
 - The percentage of switches connected to an optical network interface

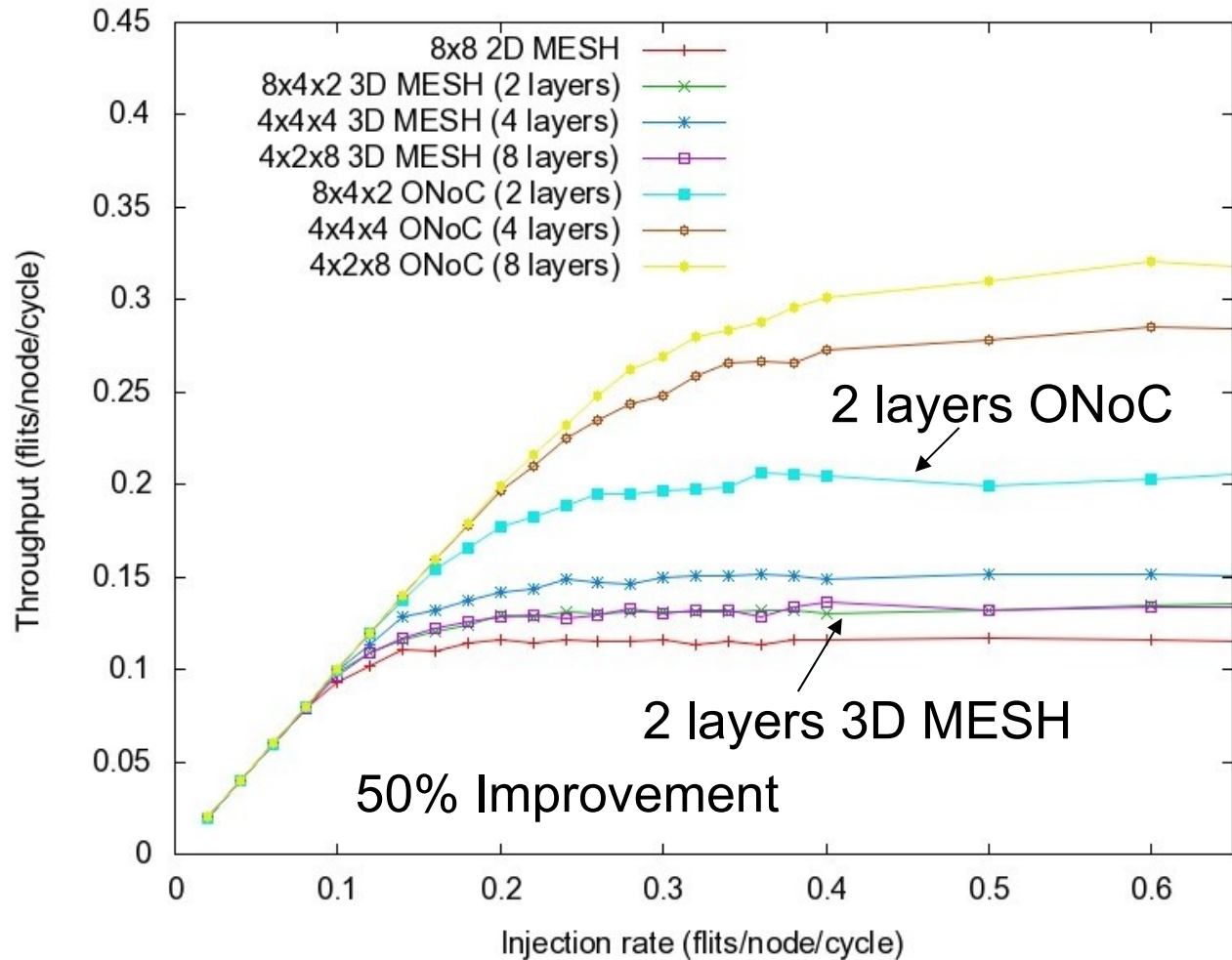
Throughput performances

- 64 nodes architectures
- Random traffic generation
- IS = 100%



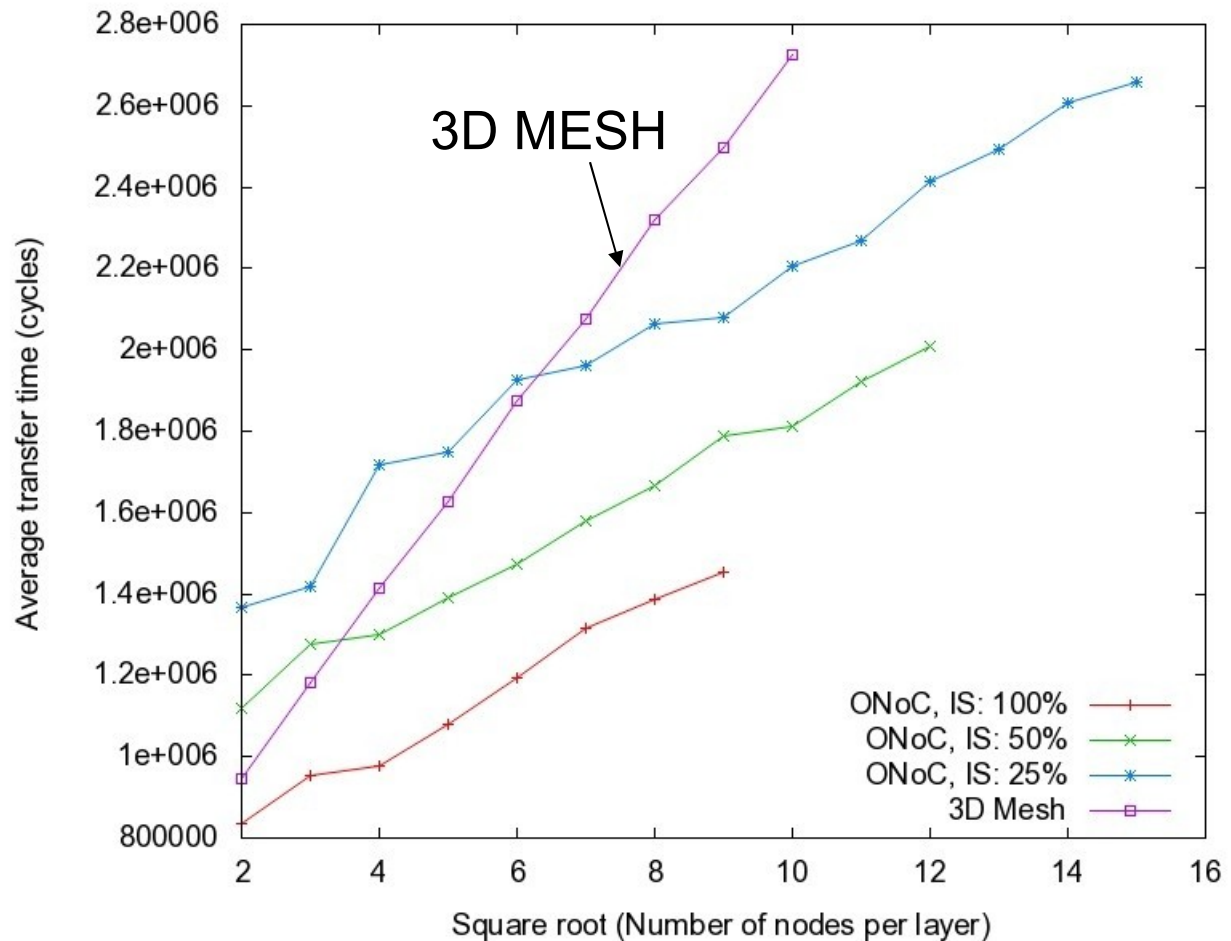
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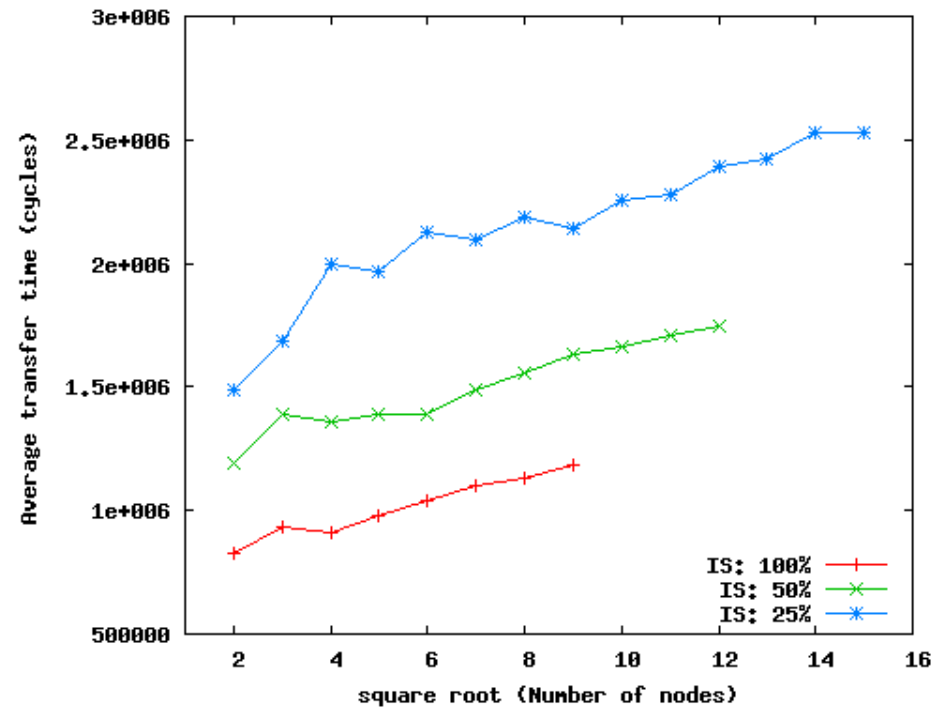
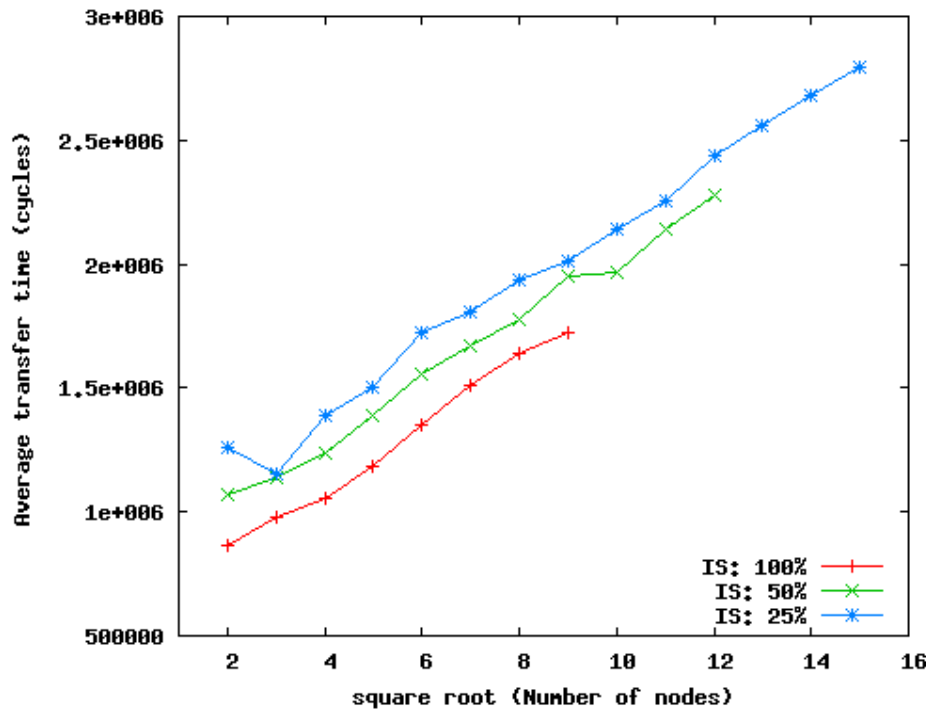


Average Transfer Time

- Injection rate = 1 (i.e. max)
- 2 electrical layers



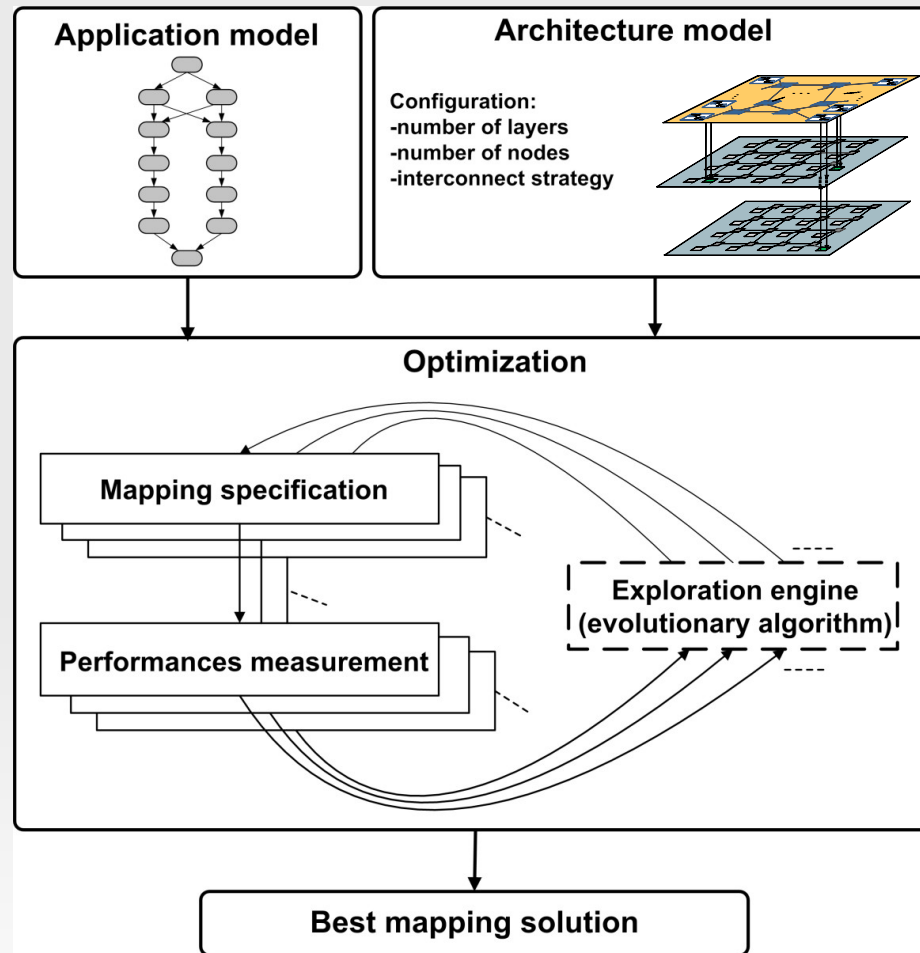
Throughput (2/2)



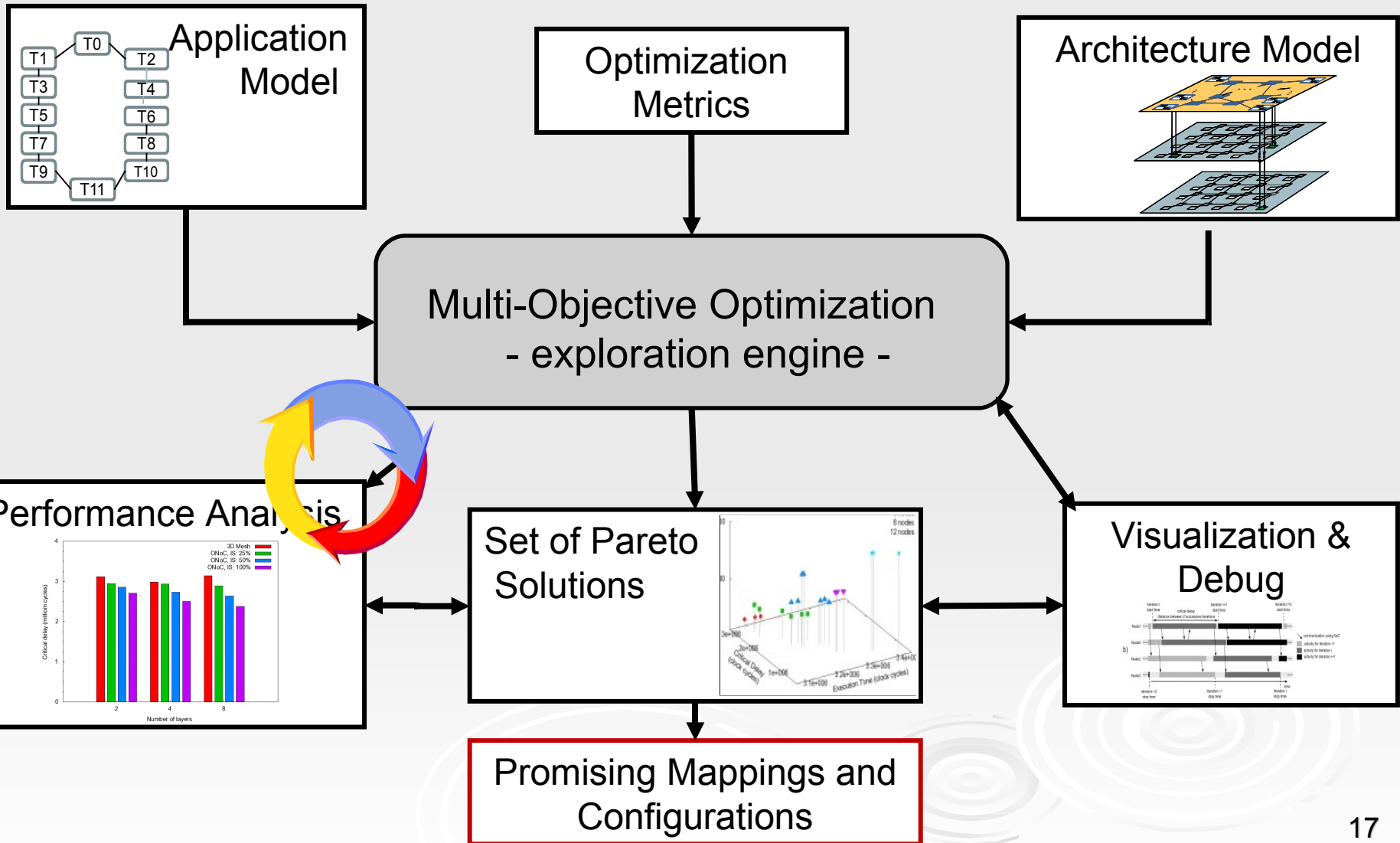
Intra-layers communication analysis

Inter-layers communication analysis

Mapping Methodology

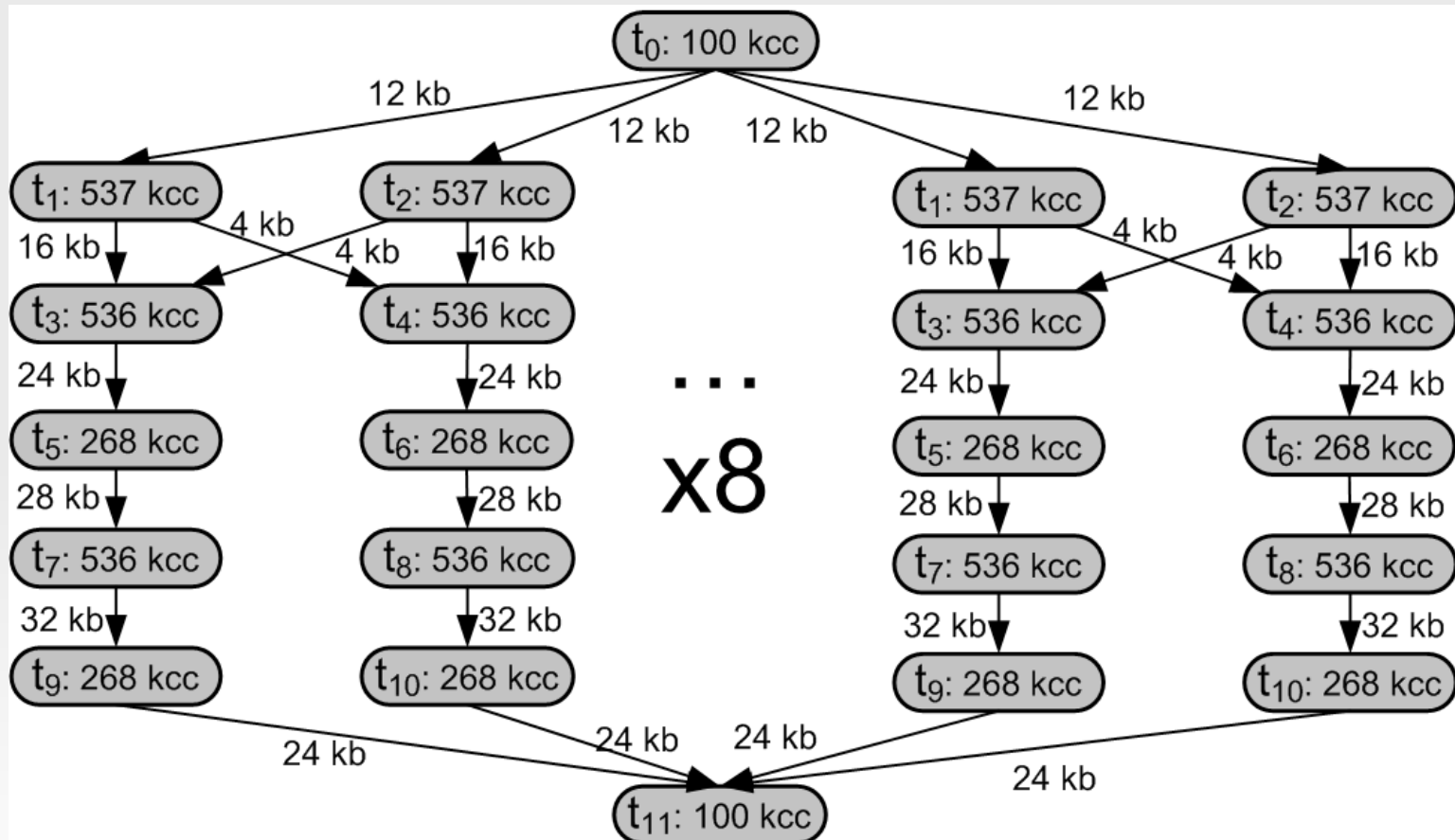


Mapping Methodology

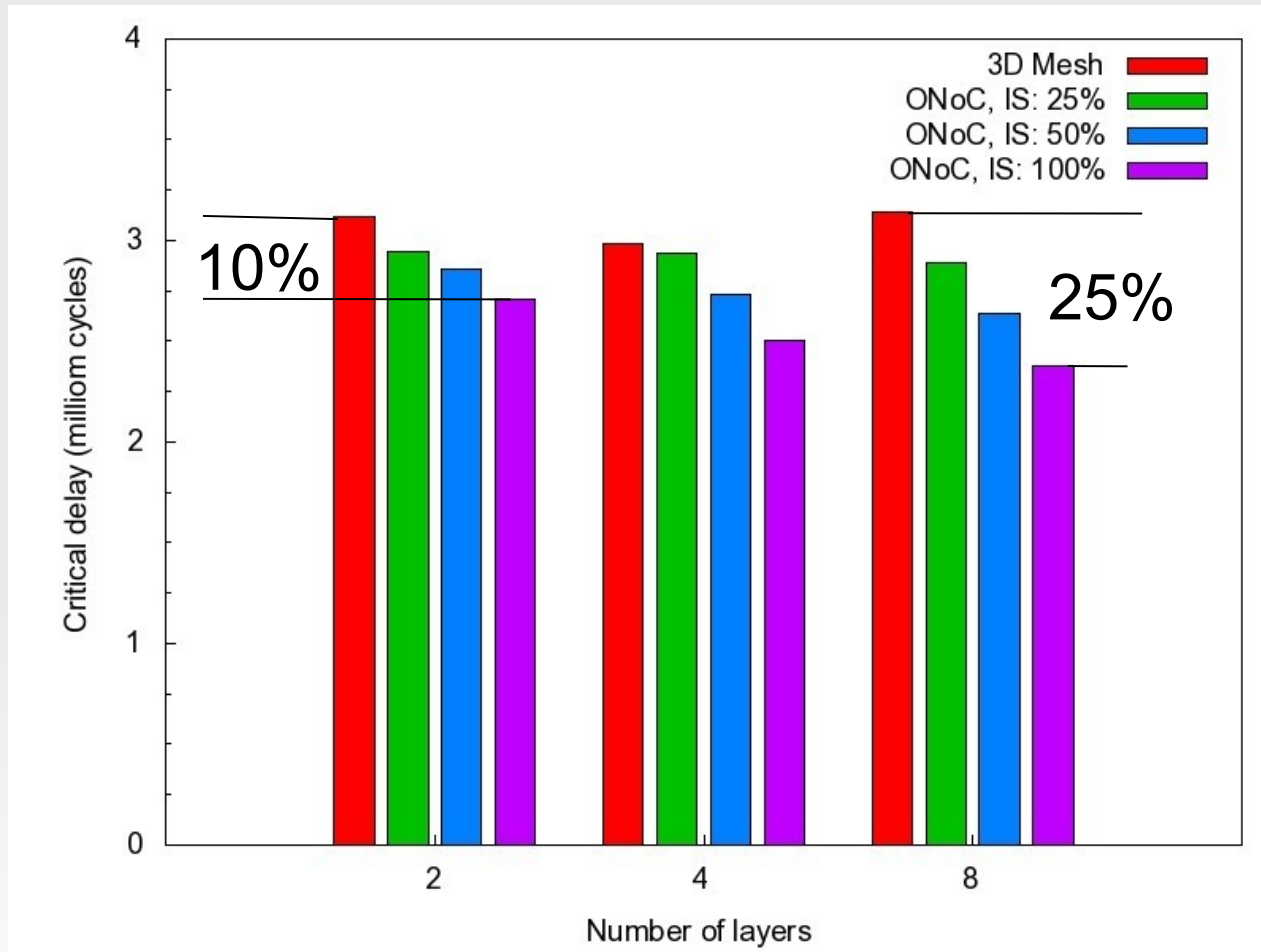


Exploration for an Image Processing Application

➤ Demosaic Application

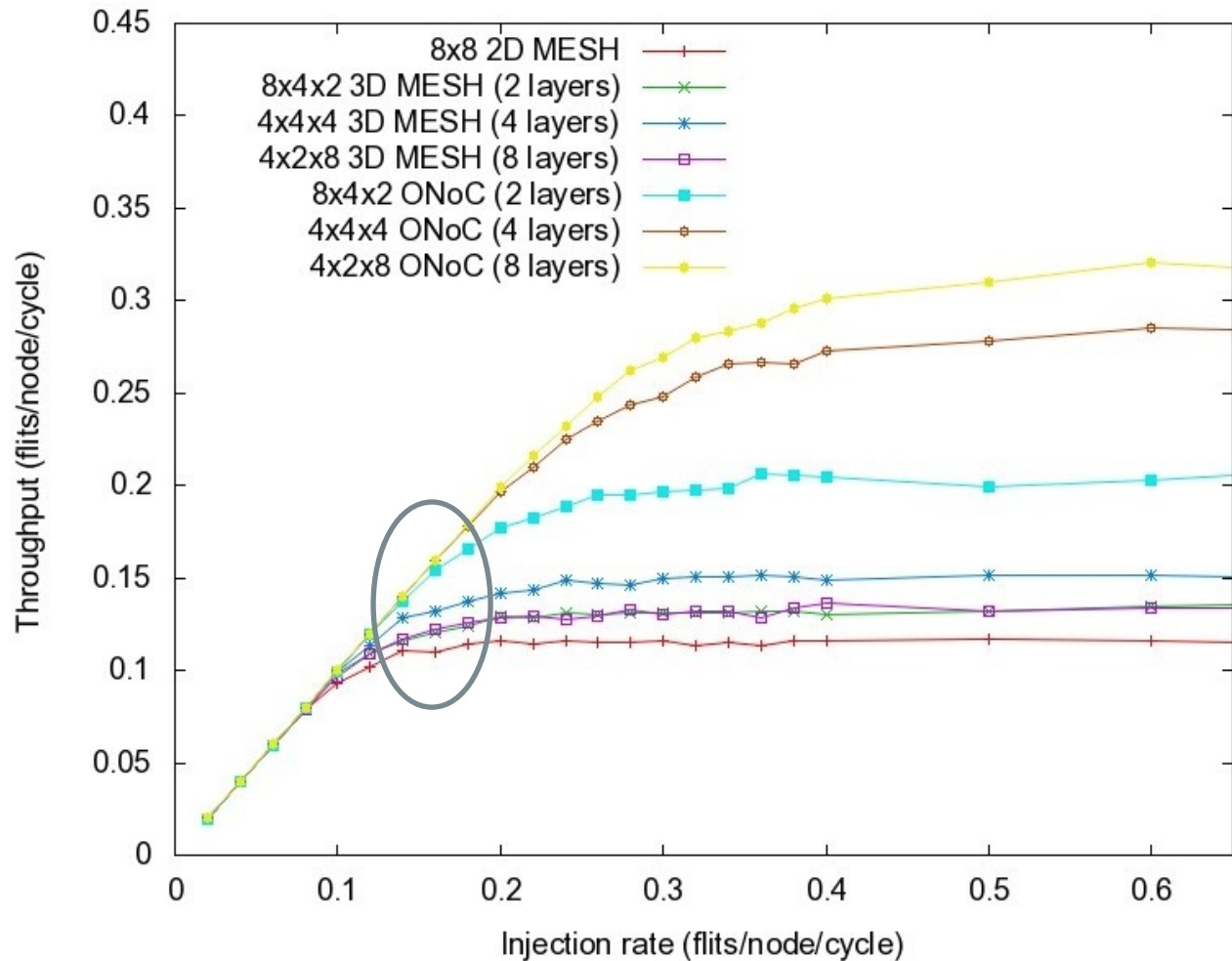


Exploration Results



Throughput performances

- 64 nodes architectures
- Random traffic generation
- IS = 100%



Summary

- 3D technology facilitates heterogeneous systems integration
- Optical Networks on Chip
 - Very Low Latency (<1ns)
 - High Bandwidth (>20GB)
 - Simplifies many-core scaling and programming model support
- System-level exploration for 3D MPSoC integrating Optical Networks on Chip
 - First prototype of a tool enabling configuration analysis
 - Automatic Application Mapping
- Demosaic example shows 10%-25% throughput improvement